



SSC8064GS6

N-Channel Enhancement Mode MOSFET

➤ Features

VDS	VGS	RDSON Typ.	ID
60V	±20V	78mR@10V	3A
		84mR@4V5	

➤ Description

This device is a N-Channel enhancement mode MOSFET which is produced with high cell density and DMOS trench technology. This device is suitable for use in battery powered system, power switch and portable devices.

➤ Applications

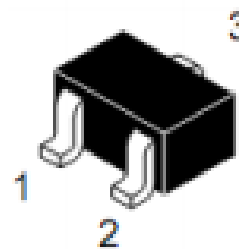
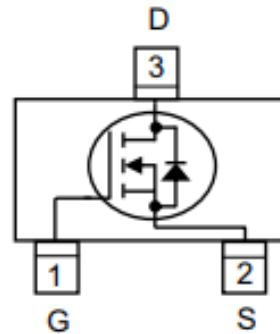
- Load Switch
- Portable Devices
- Battery Powered System

➤ Ordering Information

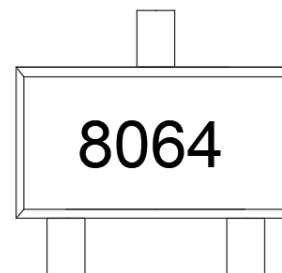
Device	Package	Shipping
SSC8064GS6	SOT23	3000/Reel

➤ Pin configuration

Top view



SOT23



Marking



➤ **Absolute Maximum Ratings**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	60	V
V_{GSS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current ^a	3	A
I_{DM}	Pulsed Drain Current ^b	12	A
P_D	Power Dissipation ^a	1.0	W
T_J	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	116.5	$^{\circ}\text{C}/\text{W}$

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design.
- Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^{\circ}\text{C}$.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using steady state junction-to-ambient thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

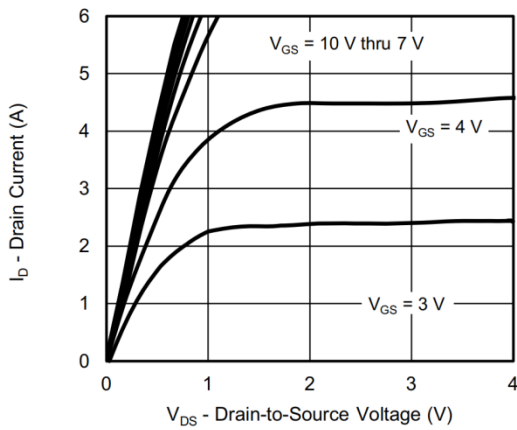


➤ **Electronics Characteristics**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

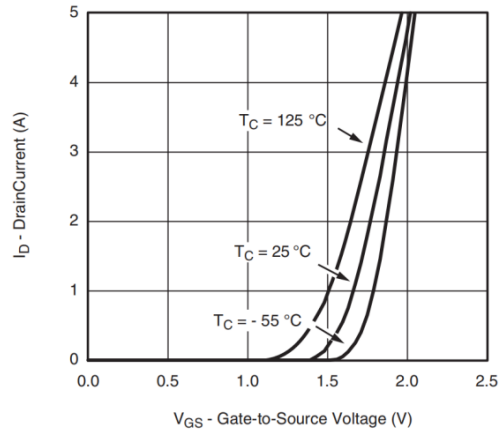
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.4	2.0	V
$R_{DS(on)}$	Drain-Source On- Resistance	$V_{GS}=10V, I_D=3A$		76	100	m Ω
		$V_{GS}=4.5V, I_D=3A$		84	120	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$			1	μA
I_{GSS}	Gate-Source leak current	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
G_{FS}	Transconductance	$V_{DS}=5V, I_D=3A$		5		S
V_{SD}	Forward Voltage	$V_{GS}=0V, I_S=3A$		0.8	1.4	V
R_g	Gate Resistance	$V_{GS}=0V, f=1MHz$		6.0		Ω
C_{iss}	Input Capacitance	$V_{DS}=30V, V_{GS}=0V,$ $f=1MHz$		402		pF
C_{oss}	Output Capacitance			35		
C_{rss}	Reverse Capacitance			24		
$T_{D(ON)}$	Turn-on delay time	$V_{DS}=30V,$ $V_{GEN}=10V, R_L=10\Omega$ $R_G=3\Omega$		3.3		ns
T_r	Rise Time			3.0		
$T_{D(OFF)}$	Turn-off delay time			22		
T_f	Fall Time			7		
Q_g	Total Gate charge	$V_{GS}=10V, V_{DS}=30V$ $I_D=3A$		8.2		nC
Q_{gs}	Gate Source charge			1.0		
Q_{gd}	Gate Drain charge			1.5		
T_{rr}	Diode Recovery Time	$I_F=3A,$ $di/dt=100A/\mu s, V_R=30V$		19.5		ns
Q_{rr}	Diode Recovery Charge	$I_F=3A,$ $di/dt=100A/\mu s, V_R=30V$		11.5		nC



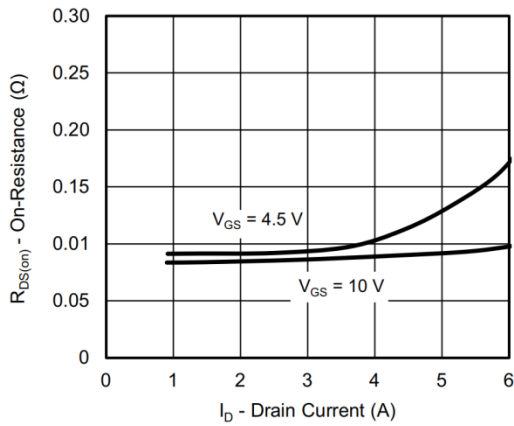
➤ **Typical Characteristics** ($T_A=25^\circ\text{C}$ unless otherwise noted)



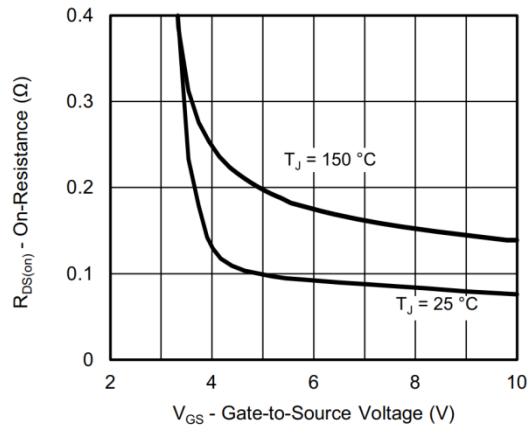
Output Characteristics



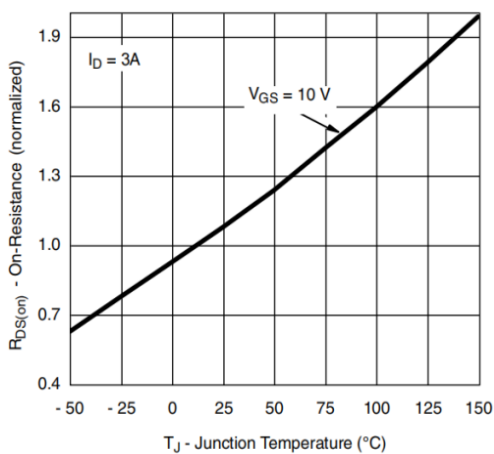
Transfer Characteristics



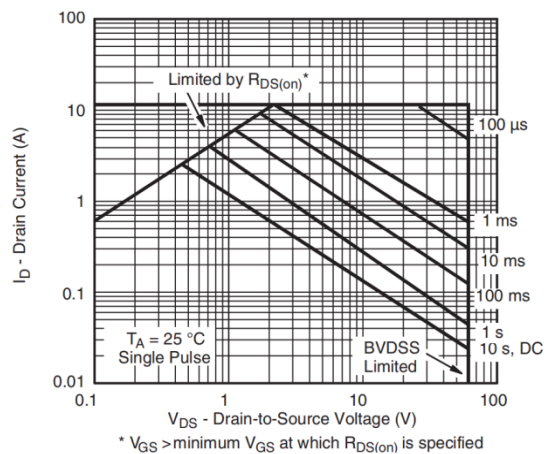
On-Resistance vs. Drain Current and Gate Voltage



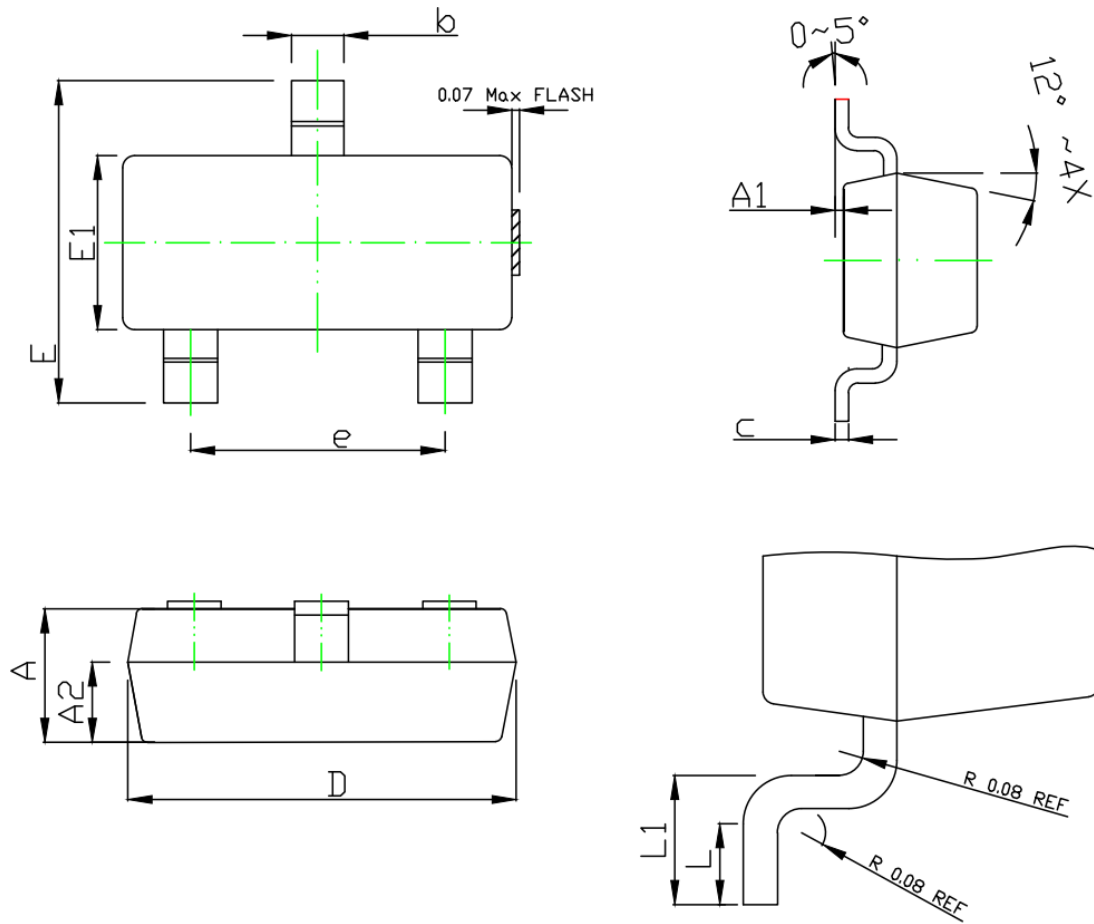
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



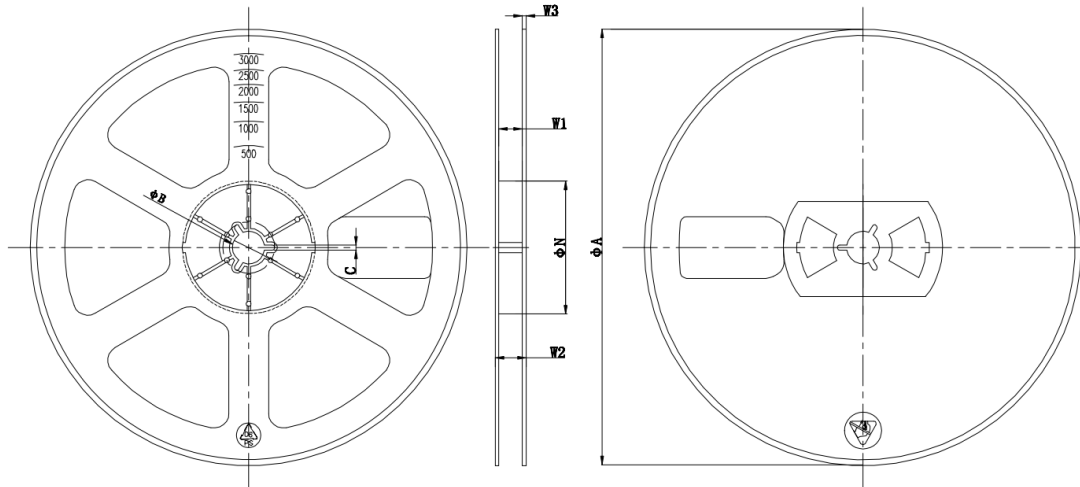
Safe Operating Area, Junction-to-Ambient

➤ Package Information


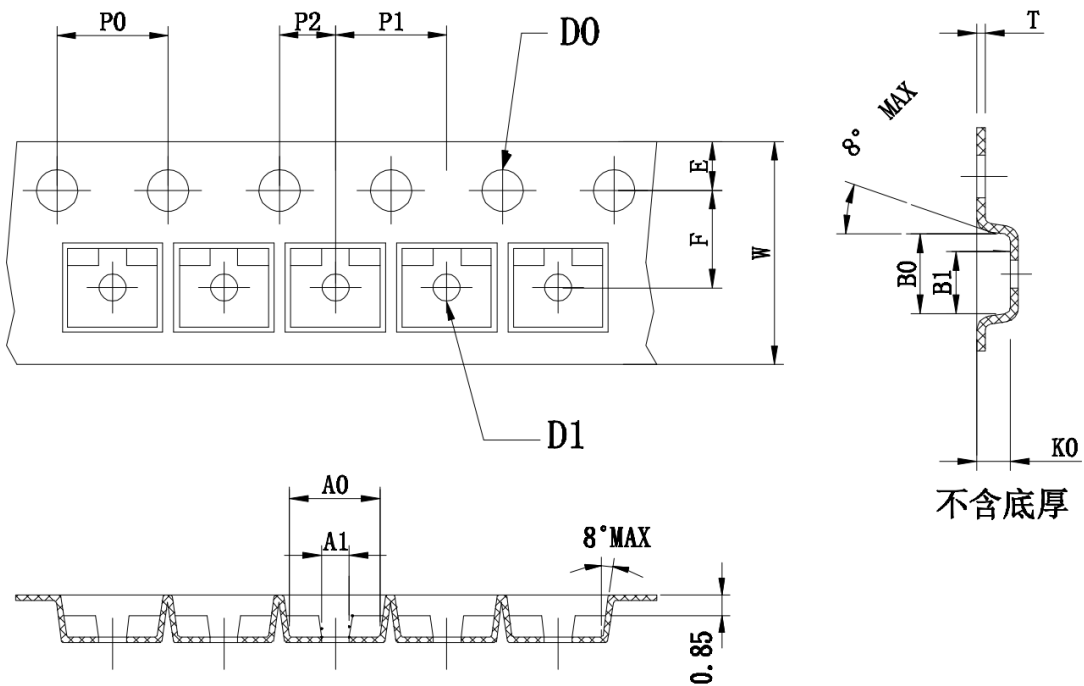
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.95	1.00	1.05
A1	0.01	0.05	0.10
b	0.35	0.40	0.45
c	0.11 BSC		
D	2.80	2.90	3.00
E	2.30	2.40	2.50
E1	1.20	1.30	1.40
e	1.90 BSC		
L	0.20	-	-
L1	0.30	0.40	0.50
A2	0.60 REF		



➤ Tape and Reel



ϕA	ϕN	ϕB	C	W1	W2	W3
178±2	54±2	13.2±0.3	2.2±0.3	9.5±1	13 _{max}	1.4±0.4



Symbol	A0	A1	B0	B1	K0	D0	D1	P0
Spec	3.15±0.10	1.15±0.10	2.80±0.10	2.15±0.10	1.30±0.10	1.55±0.10	1.10±0.10	4.00±0.10
Symbol	P1	W	E	P2	T	10*P0	F	
Spec	4.00±0.10	8.00±0.10	1.75±0.10	2.00±0.10	0.21±0.02	40.00±0.10	3.50±0.10	



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